IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Inform	ation														
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
n Semiconductor												2021-02-04			
Contact Name			Title - Contact			F	Phone - Contact*					Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			]	NA					Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			F	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
Requester	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date	Versi	on	Manufacturing Site		V	Veight*	UOM	Unit Type
		MUR1560G R		REC T0220 15A 600V ULTFST			2021-02-04			CN5		19	962.01	mg	Each
	Process Informatio														
8					-STD-020 MSI	L Rating	Peak Process Body Temperatur			me at Peak	T .		er of Reflow Cyc	eles	
Matte Tin	(Sn) - annealed	C	U Alloy	N	VA.		0		C	30		second	ls  3		
omments															
r more informatio	on regarding material co	mposition p	please refer to	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its products a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	A	Lead (Pb)	7439-92-1	7a	74.682	mg
			Supplier	Tin (Sn)	7440-31-5		8.298	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9	mg		Metal Hydroxide	proprietary data		38.073	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.925	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		81.585	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		13.5975	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg